







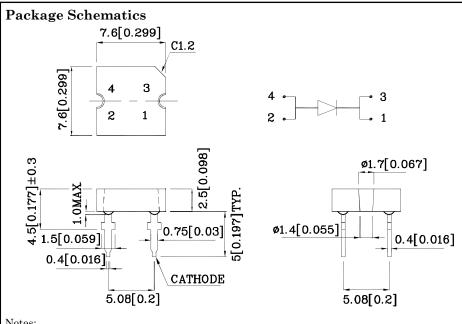
- High current operation for greater luminous output
- Low power consumption and thermal resistance

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- Can be used with automatic insertion equipment
- RoHS Compliant







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		M2ACR (AlGaInP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V		
Forward Current	I_{F}	30	mA mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150			
Power Dissipation	P_{D}	84	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

Operating Characteristics (T _A =25°C)	M2ACR (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.8	V
Reverse Current (Max.) $(V_R=5V)$	I_{R}	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λР	640*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	625*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	25	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	27	рF

Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}20\text{mA}) \ mcd \end{array}$		Luminous Flux CIE127-2007* (I _F =20mA) mlm	Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
				min.	typ.	typ.		
XSM2ACR383W	Red	AlGaInP	Water Clear	400 200*	895 500*	1600*	640*	110°

- 1. θ 1/2 Is the angle from optical centerline where the luminous intensity is 1/2 the optical peak value.
- 2. Drive current between 10mA and 30mA are recommended for long term performance.
- 3. Operation at current below 10mA is not recommended.
- 4. LEDs are binned according to their Luminous intensity.
- * Luminous intensity / luminous flux value and wavelength are in accordance with CIE127-2007 standards.

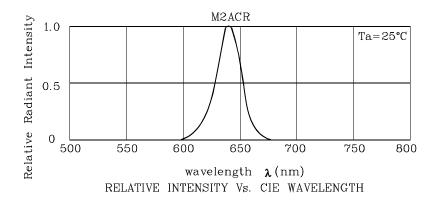
May 08,2012 XDSB5608 V2-X Layout: Maggie L.

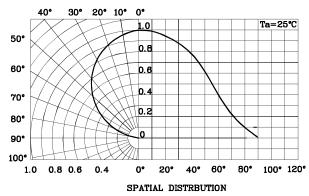


Part Number: XSM2ACR383W

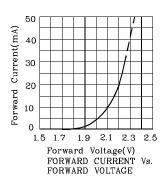
SUPER FLUX LED LAMP

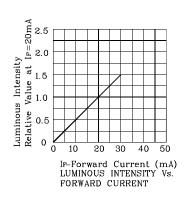


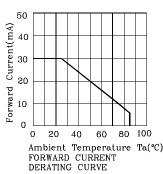


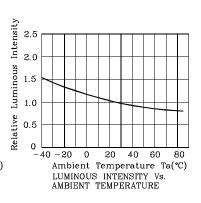


❖ M2ACR

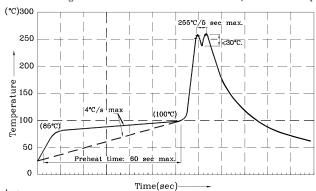








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes: Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C$ \sim $255^{\circ}C$ for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above $85\,^{\circ}\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS

